

Title (en)

POTTING COMPOUND, USE THEREOF AND COMPONENTS ENCAPSULATED IN SAID POTTING COMPOUND

Title (de)

VERGUSSMASSE, VERWENDUNG DAZU UND MIT DER VERGUSSMASSE UMHÜLLTE BAUELEMENTE

Title (fr)

MASSE DE SCELLEMENT, SON UTILISATION, ET COMPOSANTS ENROBES DE CETTE MASSE DE SCELLEMENT

Publication

EP 1668078 A1 20060614 (DE)

Application

EP 04766551 A 20040820

Priority

- EP 2004051852 W 20040820
- DE 10345544 A 20030930

Abstract (en)

[origin: WO2005033203A1] The invention relates to a potting compound based on epoxy resins, which comprise mixtures of bisphenol-F and bisphenol-A diglycidyl ethers and highly functional epoxy-phenol novolaks. A blend of two hardener components, an amine and an imidazole component is added to the potting compound as a hardener, both hardener components having a solid form at ambient temperature. The potting compound contains a filler with a multi-modal particle size distribution, which has been optimised to produce the maximum fill degree possible with the minimum viscosity possible. Said potting compound remains stable during storage at ambient temperature for several months and can nevertheless be processed at a moderately increased temperature with a good pot life. After being subjected to stress, constant thermomechanical characteristics can be guaranteed for the potting compound over a wide temperature range.

IPC 1-7

C08L 63/00; **H01L 23/29**

IPC 8 full level

C08G 59/50 (2006.01); **C08L 63/00** (2006.01); **H01L 23/29** (2006.01)

CPC (source: EP)

C08G 59/50 (2013.01); **C08L 63/00** (2013.01); **H01L 23/293** (2013.01); **H01L 2924/0002** (2013.01)

Citation (search report)

See references of WO 2005033203A1

Designated contracting state (EPC)

DE FR GB

DOCDB simple family (publication)

WO 2005033203 A1 20050414; EP 1668078 A1 20060614

DOCDB simple family (application)

EP 2004051852 W 20040820; EP 04766551 A 20040820